

As pointed out by Applicant's counsel in the telephone interview of September 6, 2001 and agreed to by the Examiner, "device" claims 24-25 and 39 in Group I are actually method claims as they refer to a step in a preceding method claim. These claims have been amended so that the preamble designates them as method claims.

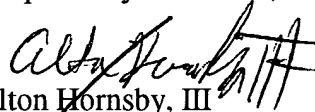
In the office action, the Examiner suggested that the device claims (Group I) and the method claims (Group II) were distinct because "the device can include terminals on the sides of the electronic device whereas the method describes an invention made with terminals on the bottom of the electronic device." Such a distinction does not correspond to method claims 38 and 39 which require a method of packaging a device having "a second terminal located at a region other than the device top."

Therefore, applicant respectfully requests that the Examiner include method claims 38-39 in Group I and method claims 24-25 in Group II.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned "**Version with markings to show changes made.**"

If the Examiner has any questions he is encouraged to contact Applicant's attorney at the below-listed number.

Respectfully submitted,


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VERSION WITH MARKINGS TO SHOW CHANGES MADE

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Claims 24-25 and 39 have been amended as follows:

24. (Amended) [An electronic component] The method according to claim 23, wherein the step of applying the conductive material comprises:

- applying a first layer of titanium;
- applying a second layer of copper on the first layer; and
- applying a third layer of chrome on the second layer.

25. (Amended) [An electronic component] The method according to claim 23, wherein the step of applying the dielectric into the recess comprises:

- applying a dry etch bisbenzocyclobutene dielectric;
- removing the dry etch bisbenzocyclobutene dielectric from the top terminal and a part of the conductive layer;
- applying a photo definable bisbenzocyclobutene dielectric; and
- exposing the top terminal and the part of the conductive layer.

39. (Amended) [An electronic component] The method according to claim 38, wherein the step of applying the layer of electrically conductive material comprises:

- applying a first layer of titanium;
- applying a second layer of copper on the first layer; and
- applying a third layer of chrome on the second layer.